

## PRODUCT / PROCESS CHANGE NOTIFICATION

### 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		ADG/18/11016
1.3 Title of PCN		PowerFLAT™ 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China)
1.4 Product Category		Power MOSFET
1.5 Issue date		2018-07-25

### 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Paolo PETRALI
2.1.3 Quality Manager	Vincenzo MILITANO

### 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Solder ball composition	ASE-WEIHAI (China)

### 4. Description of change

	Old	New
4.1 Description	Selected products in PowerFLAT™ 8x8 HV, are manufactured by ASE-WEIHAI (China) Subcontractor with Power Glue in the Die Attach Process.	Selected products in PowerFLAT™ 8x8 HV, are manufactured by ASE-WEIHAI (China) Subcontractor with Solder Paste in the Die Attach Process.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no impacts	

### 5. Reason / motivation for change

5.1 Motivation	Improve Quality
5.2 Customer Benefit	QUALITY IMPROVEMENT

### 6. Marking of parts / traceability of change

6.1 Description	will be identified by the additional info "P" marked on the package and internal code reported in the Box Label of the packing.
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### 7. Timing / schedule

7.1 Date of qualification results	2018-07-18
7.2 Intended start of delivery	2018-10-28
7.3 Qualification sample available?	Upon Request

### 8. Qualification / Validation

8.1 Description	11016 Rel14-18.pdf	
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date 2018-07-25

**9. Attachments (additional documentations)**

11016 Public product.pdf  
11016 PowerFLAT&#8482; 8x8 HV New Die Attach process & material from Power Glue to Solder Paste.pdf  
11016 Rel14-18.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	STL26NM60N	
	STL33N60DM2	
	STL33N60M2	
	STL33N65M2	
	STL36N55M5	
	STL38N65M5	
	STL57N65M5	

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Dear Customer,

Following the continuous improvement of our Quality and Reliability, we are going to change the Die Attach process and compound from Power Glue to Solder Paste of Power MOSFET Transistors listed in this PCN. Products with new process/material, guarantee the same electrical characteristics as reported in the relevant data sheets. Devices used for qualification are available as Samples.

The involved product series and affected packages are listed in the table below:

Product Family	Package	Commercial Product / Series
Power MOSFET Transistors	PowerFLAT™ 8x8 HV	STLxxxxxxxx

Any other Product related to the above series, manufactured in PowerFLAT™ 8x8 HV Package, even if not expressly included or partially mentioned in the attached table, is affected by this change.

**Qualification program and results availability:**

The reliability test report is provided in attachment to this document.

**Samples availability:**

Samples of the test vehicle devices will be available on request starting from week 28-2018. Any other sample request will be processed and scheduled by Power Transistor Division upon request.

Product Family Description	Part Number - Test Vehicle
Power MOSFET Transistors	STL57N65M5 STL33N60M2

**Change implementation schedule:**

The production start and first shipments will be implemented according to our work in progress and materials availability:

Product Family Description	1st Shipments
Power MOSFET Transistors	From Week 41-2018

Lack of acknowledgement of the PCN within 30 days will constitute acceptance of the change. After acknowledgement, lack of additional response within the 90 days period will constitute acceptance of the change (Jedec Standard No. 46-C). In any case, first shipment may start earlier with customer written agreement.

**Marking and traceability:**

Unless otherwise stated by customer specific requirement, traceability of PowerFLAT™ 8x8 HV Package manufactured with new process/material, will be identified by internal code and the additional info “P” marked on the package.

Sincerely Yours.





## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCN Title :** PowerFLATTM 8x8 HV New Die Attach process & material from Power Glue to Solder Paste - ASE-WEIHAI (China)

**PCN Reference :** ADG/18/11016

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STL45N65M5	STL57N65M5	STL38N65M5
STL33N60M2	STL36N55M5	STL26NM60N
STL33N60DM2	STL33N65M2	



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